

For first time, there was an exhibition taken place during the conference. The following companies participated in the conference exhibition: Hitachi Chemicals, Panasonic, Henkel, STS, Hirox, Pac-Tech and Sang Yuen. Three best Intel student awards were to given to the students from Dalian University of Science and Technology, University of Science and Technology, Beijing and Hua Zhong University of Science and Technology, China. The HDP'07 conference provided an excellent opportunity for the microelectronics and microsystem industries to exchange the latest development in this fascinating field, especially with regard to the rapid growth of electronics industry in China.

In addition to this, three short courses were given by Prof. C.P. Wong, Prof. James Morris, Dr. Shangguan Dongkai, Dr. Fay Hua and Dr. Daniel Lu on nanotechnology as well as on lead free technology including solders and conductive adhesives.

Workshop Reviews:

Call for Participation in the 2007 IEEE/CPMT Workshop on Accelerated Stress Test and Reliability

Greenbelt Marriot in Greenbelt, Maryland
October 31st through November 2nd, 2007
Submitted by Kirk Gray, Dell Reliability Validation
Engineer, Tel: 512-723-1374

This year's IEEE/CPMT Workshop on Accelerated Stress Test and Reliability Theme is: "Accelerated Life Testing, it's Role, Challenges, Attributes, and Interaction with Qualification Testing". Over the last few decades, Accelerated Stress Testing (AST) has been embraced by an ever widening array of worldwide companies seeking to reconcile the need for the highest quality product with the necessary push for early time-to-market. The purpose of the AST Workshop is to share ideas on better ways of accelerated testing, stress margin limit testing and analysis, and detecting hidden defects and weaknesses in electronic and electro-mechanical hardware that would result in failures. The goal of AST is to cost effectively develop mature robust products at market introduction.

You can access all the current Workshop information at our Website at www.ewh.ieee.org/soc/cpmt/tc7/ast2007/

Our registration page can be linked from the home page or accessed directly at URL:

icm3.ieee.org/eventmanager/online/registration.asp?eventcode=9L6

Just some of the Presentations that are scheduled at this year's event:

Paul Parker	Power Supply Design and Test for Reliability
Ali Shakouri	Reliability and Testing on Nanostructure
Mike Silverman	Early Reliability Testing
Gary M. Hazard	Rapid Reliability Risk Assessment for Fiber Optic Components
Don Gerstle	Power Conversion Reliability

Hong S. Liu

R.Zingher et al.

Gustavo Plaza et al.

Mike Silverman Hass

David Francis

Koustav Sinha et al.

Gayatri Cuddalorepatta et al.

Jinsong Xie

Joey Bernstein et al.

Comparison Testing of Shock vs. Vibration ESS system

Enhancing Accelerated Life tests with monitoring and prognostication

Study of Vibration Monitoring and Failure Criteria Definition for Solder Interconnect

Profile Fine Tuning Using Field Data

Case Study at CNH Case New Holland - HALT of Alternators

Mechanical strength of copper-silicon interface of planar metallization power modules

Durability Assessment of an Advanced Power Electronics Thermal Cooler

A Case Study of Field Life Prediction and Reliability Assessment of Electronics Assemblies

Physics of Failure and Reliability Modeling of Electronic Packages

2008 IEEE Systems Packaging Japan Workshop

Hotel de YAMA, Hakone, Japan

January 28 - 30, 2008

www.ewh.ieee.org/soc/cpmt/tc14/

Submitted by Evan Davidson, Japanese Liaison for TCSP

Call for Papers and Invitation

The Systems Packaging Japan Committee cordially invites you to participate in the 2008 IEEE Systems Packaging Japan Workshop (2008 SPJW), which will be held during January 28-30, 2008 at the Hotel de YAMA, Hakone, Japan. This workshop is held every other year in Japan and 2008 SPJW will be the twelfth one since the first workshop in 1986. State-of-the-art technologies in all areas of systems packaging from personal systems to high performance systems will be covered. Attendees are expected to be specialists in the field and to actively participate in all discussions. We look forward to meeting many of you at Hakone.

Topics:

- IT Network Systems
- Digital Consumer Products & Mobile Information Systems
- High Performance Servers
- Advanced Packaging & Components
- Bio/Nano Technologies
- Environmental Aspects

For more information about the workshop, please feel free to contact Mr. Kishio Yokouchi, the Program Chair at:

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